

Title (en)  
IMPLANT OVER DENTURE SYSTEM AND IMPLANT

Title (de)  
IMPLANTAT-ÜBER-ZAHNPROTHESE-SYSTEM UND IMPLANTAT

Title (fr)  
SYSTÈME DE PROTHÈSE HYBRIDE PAR IMPLANT, ET IMPLANT

Publication  
**EP 2881079 A4 20160420 (EN)**

Application  
**EP 13826141 A 20130604**

Priority  
• JP 2012171443 A 20120801  
• JP 2013065430 W 20130604

Abstract (en)  
[origin: EP2881079A1] An implant overdenture system 1 is used to fix an implant overdenture 3 onto alveolar ridge 8 by the support of implants 10. The implant overdenture 3 has artificial teeth 31, a denture base 32, and magnetic assemblies 4. The implants 10 each have an implant body 11 and a keeper 2. A largest circumscribed circle diameter d1 in an outer shape of a surface-to-be-attracted of the keeper 2 is equal to or larger than  $\sqrt{1.8}$  mm, and a largest diameter d2 of the implant body 11 is equal to or larger than  $\sqrt{1.2}$  mm and equal to or less than  $\sqrt{3.5}$  mm, and these largest diameters have a relationship expressed by  $d1/d2 \neq 1.5$ .

IPC 8 full level  
**A61C 13/235** (2006.01); **A61C 8/00** (2006.01)

CPC (source: EP KR US)  
**A61C 8/0074** (2013.01 - EP KR US); **A61C 8/0081** (2013.01 - EP KR US); **A61C 8/0089** (2013.01 - KR US); **A61C 8/0095** (2013.01 - EP KR US); **A61C 13/235** (2013.01 - EP KR US)

Citation (search report)  
• [XYI] US 2009117520 A1 20090507 - KIKUCHI AKIRA [JP]  
• [Y] US 2010055645 A1 20100304 - MULLALY SCOTT [US], et al  
• [X] JP 2008093126 A 20080424 - HITACHI METALS LTD  
• See references of WO 2014020985A1

Cited by  
IT201800007849A1; WO2017085584A1

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)  
**EP 2881079 A1 20150610; EP 2881079 A4 20160420**; AU 2013297857 A1 20150219; CA 2880247 A1 20140206; CA 2880247 C 20171114; CN 104507414 A 20150408; JP 2014030499 A 20140220; JP 5689855 B2 20150325; KR 102040478 B1 20191106; KR 20150036762 A 20150407; TW 201406351 A 20140216; TW I563984 B 20170101; US 2015265379 A1 20150924; US 9925023 B2 20180327; WO 2014020985 A1 20140206

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